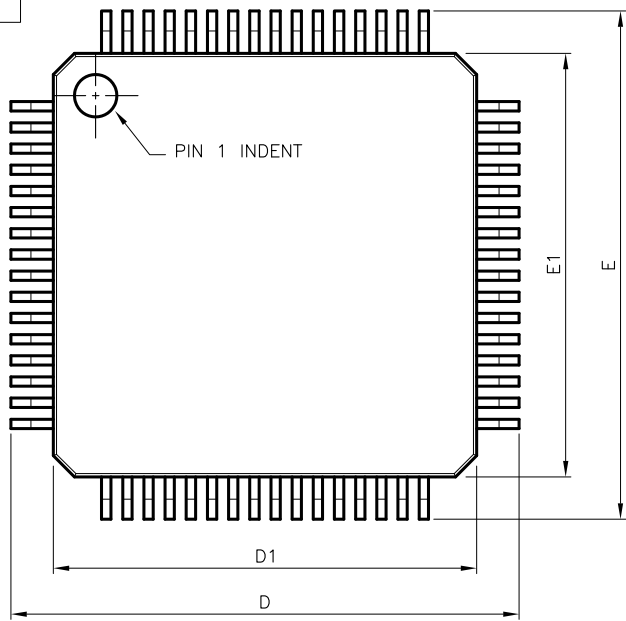
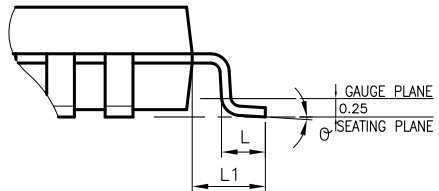
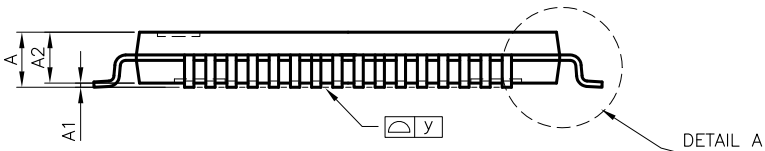
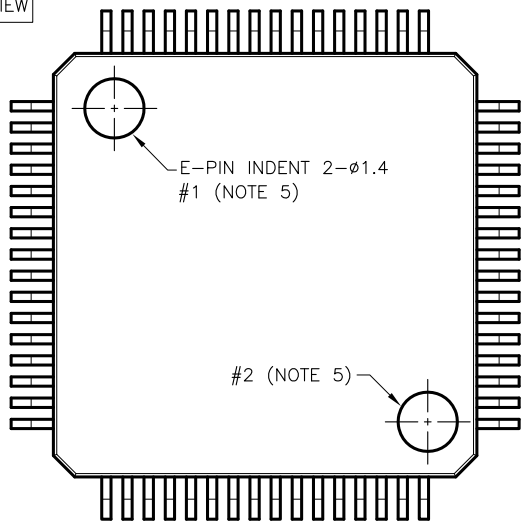
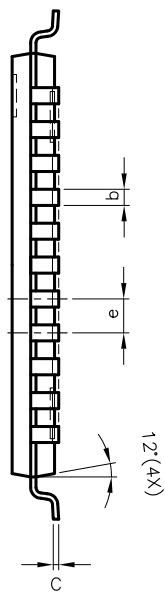


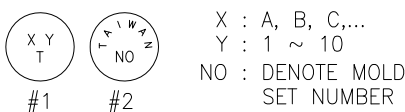
TOP VIEW



BOTTOM VIEW



- NOTE :
1. CONTROLLING DIMENSION : mm
 2. LEAD FRAME MATERIAL : COPPER C7025
 3. PACKAGE DIMENSION EXCLUSIVE MOLDING FLASH,ALLOWABLE PROTRUSION IS 0.25 mm PER SIDE
 4. RESIN PROTRUSION BETWEEN LEAD TO LEAD TO BE 0.08 mm MAX
 5. BOTTOM E-PIN INDENT ARE MARKED AS BELOW :



6. ALL EDGE CORNER TO BE R 0.20 MAX.
7. JEDEC NUMBER : MS-026

SYMBOL	DIMENSIONS IN MILLIMETERS		
	MIN.	NOM.	MAX.
A	—	—	1.20
A1	0.05	—	0.15
A2	0.95	1.00	1.05
b	0.17	0.22	0.27
C	0.09	—	0.20
E	—	12.00	—
E1	—	10.00	—
D	—	12.00	—
D1	—	10.00	—
e	—	0.50	—
L	0.45	0.60	0.75
L1	—	1.00	—
φ	0°	3.5°	7°
y	0.0	—	0.08

CUSTOMER :		LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z. PRECISION IND., LTD. TAICHUNG, TAIWAN, R. O. C.	
APPROVED BY	DATE	TITLE: 64L TQFP PACKAGE OUTLINE DRAWING(10x10x1.0 mm) (2.0 mm FOOTPRINT)	
DRAW BY: <i>Vicky Chen</i>	<i>07/21/98</i>		
CHECK BY: <i>Thomas Kao</i>	<i>7/24/98</i>	DWG. NO.	PO-TQFP-005
APPROVAL: <i>Paul Liu</i>	<i>7/30/98</i>	REV.	0
APPROVAL: <i>Barry Chen</i>	<i>7/31/98</i>	UNIT :	mm
		SCALE :	8/1
		SHEET	1 OF 1